

#### **DESCRIPTION**

The IS281 series optocoupler consists of an infrared emitting diode optically coupled to an NPN silicon photo transistor.

This device belongs to Isocom Compact Range of Optocouplers.

#### **FEATURES**

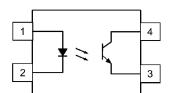
- Half Pitch 1.27mm
- High AC Isolation voltage 3750V<sub>RMS</sub>
- CTR Selections Available
- Wide Operating Temperature Range -55°C to 110°C
- Pb Free and RoHS Compliant
- UL Approval E91231, Model "THP"

#### **APPLICATIONS**

- Switching Mode Power Supply
- Industrial System Controllers
- Measuring Instruments
- Signal Transmission between Systems of Different Potentials and Impedances

#### ORDER INFORMATION

 Available in Tape and Reel with 1000pcs per reel





- Anode
- 2 Cathode
- 3 Emitter
- 4 Collector

#### ABSOLUTE MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Stresses exceeding the absolute maximum ratings can cause permanent damage to the device.

Exposure to absolute maximum ratings for long periods of time can adversely affect reliability.

#### Input

Forward Current	50mA
Reverse Voltage	6V
Power dissipation	70mW

### Output

Collector to Emitter Voltage BV<sub>CEO</sub> 80V

Emitter to Collector Voltage BV<sub>ECO</sub> 7V

Collector Current 50mA

Power Dissipation 150mW

#### Total Package

Isolation Voltage 3750V<sub>RMS</sub>

Total Power Dissipation 200mW

Operating Temperature -55 to 110 °C

Storage Temperature -55 to 150 °C

Lead Soldering Temperature (10s) 260°C

#### **ISOCOM COMPONENTS 2004 LTD**

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# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise specified)

## **INPUT**

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward Voltage	$V_{\mathrm{F}}$	$I_F = 20 \text{mA}$		1.2	1.4	V
Reverse Current	$I_R$	$V_R = 4V$			10	μΑ
Terminal Capacitance	$C_{IN}$	V = 0V, $f = 1KHz$		30	250	pF

## **OUTPUT**

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Collector-Emitter Breakdown Voltage	$BV_{CEO}$	$I_C = 0.1 \text{mA}, I_F = 0 \text{ mA}$	80			V
Emitter-Collector Breakdown Voltage	$\mathrm{BV}_{\mathrm{ECO}}$	$I_E = 0.1 \text{mA}, I_F = 0 \text{mA}$	7			V
Collector-Emitter Dark Current	$I_{CEO}$	$V_{CE} = 20V$ , $I_F = 0mA$			100	nA



# **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise specified)

### **COUPLED**

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit	
Current transfer ratio	CTR	$I_F = 5mA$ , $V_{CE} = 5V$				%	
		IS281	50		600		
		IS281A	80		160		
		IS281B	130		260		
		IS281C	200		400		
		IS281D	300		600		
		IS281E	100		200		
		IS281F	150		300		
		$I_F = 10 \text{mA}, V_{CE} = 5 \text{V}$					
		IS281H	40		80		
		IS281I	63		125		
		IS281J	100		200		
		IS281K	160		320		
		IS281GR	100		300		
		IS281GB	100		600		
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	$I_F = 10 \text{mA}, I_C = 1 \text{mA}$		0.1	0.2	V	
Floating Capacitance	$C_{\mathrm{f}}$	$V_F = 0V$ , $f = 1MHz$	$V_F = 0V, f = 1MHz$ 0.3		pF		
Output Rise Time	$t_{\rm r}$	$V_{CE} = 2V$ , $Ic = 2mA$ , $R_L = 100\Omega$		6	18	μs	
Output Fall Time	$t_{\mathrm{f}}$	$V_{CE} = 2V$ , $Ic = 2mA$ , $R_L = 100\Omega$		6	18	μs	

## **ISOLATION**

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Isolation Voltage	V <sub>ISO</sub>	R.H. = 40% to 60%, t = 1 min Note 1	3750			$V_{RMS}$
Input - Output Resistance	R <sub>I-O</sub>	$V_{I-O} = 500 VDC$ R.H. = 40% to 60% Note 1	5x10 <sup>10</sup>			Ω

Note 1: Measured with input leads shorted together and output leads shorted together.



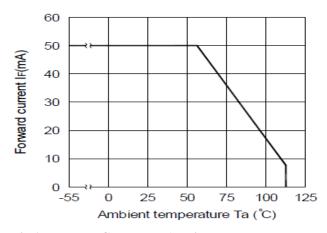


Fig 1 Forward Current vs Ambient Temperature

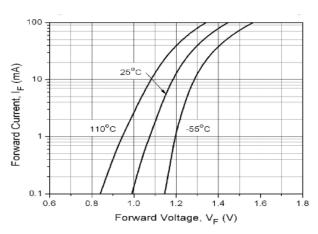


Fig 3 Forward Current vs Forward Voltage

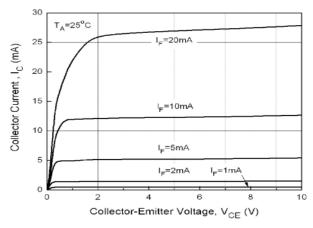


Fig 5 Collector Current vs Collector-Emitter Voltage (1)

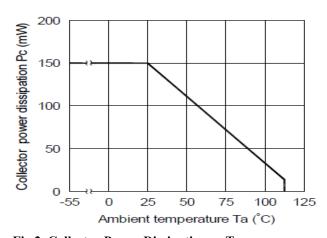


Fig 2 Collector Power Dissipation vs  $T_A$ 

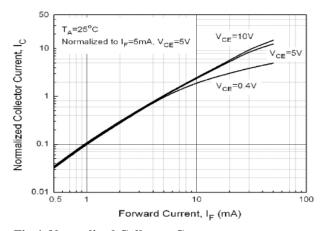


Fig 4 Normalized Collector Current vs Forward Current

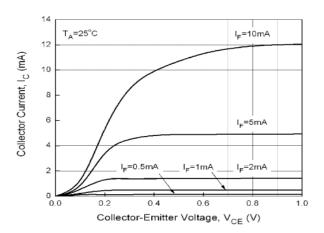


Fig 6 Collector Current vs Collector-Emitter Volatge (2)



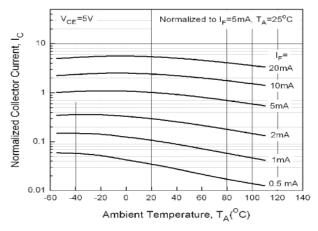


Fig 7 Normalized Collector Current vs Ambient Temperature

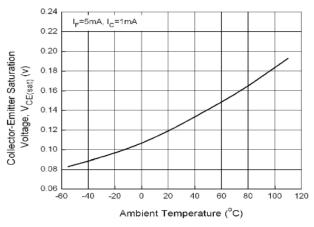


Fig 9 Collector-Emitter Voltage vs Ambient Temperature

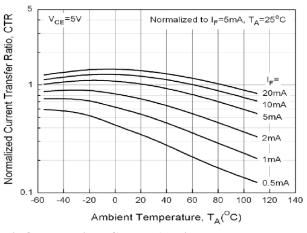


Fig 8 Normalized CTR vs Ambient Temperature

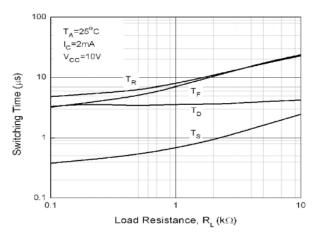
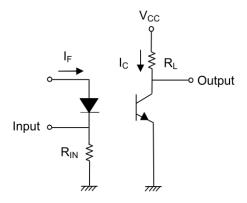
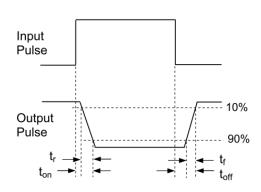


Fig 10 Switching Time vs Load Resistance



**Switching Time Test Circuit** 

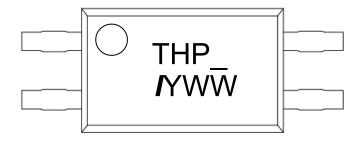




### **ORDER INFORMATION**

	IS281				
After PN	PN	Description	Packing quantity		
None	IS281	Surface Mount Tape & Reel	1000 pcs per reel		
Any CTR Grade	IS281A, IS281B, IS281C, IS281D, IS281E, IS281F, IS281H, IS281I, IS281J, IS281K, IS281GR, IS281GB	Surface Mount Tape & Reel	1000 pcs per reel		

### **DEVICE MARKING**



THP\_ denotes Device Part Number where "\_" denotes CTR Grade

Optional Marking : for IS281B, Marking can be THP3

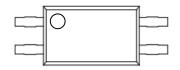
denotes Isocom

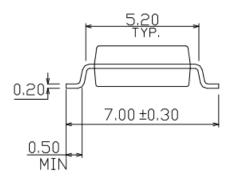
Y denotes 1 digit Year code

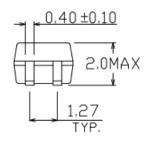
WW denotes 2 digit Week code



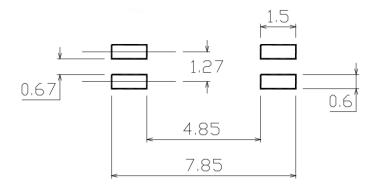
## **PACKAGE DIMENSIONS (mm)**





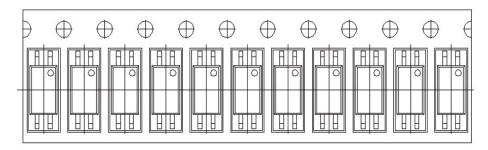


## **RECOMMENDED SOLDER PAD LAYOUT (MM)**



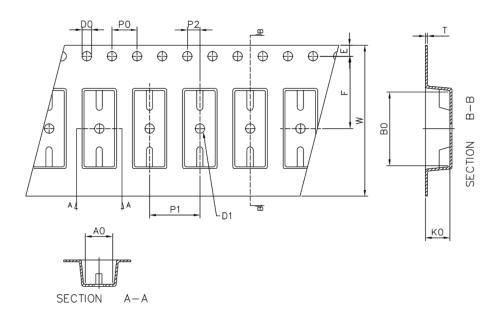


## Tape and Reel Packaging





# Direction of feed from reel

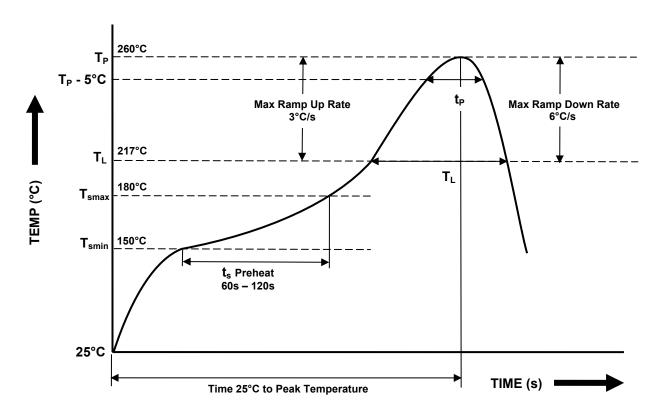


Dimension No.	A0	В0	D0	D1	E	F
Dimension( mm)	3.00±0.10	7.45±0.10	1.50+0.1/-0	1.50±0.10	1.75±0.10	5.5±0.10
Dimension No.	P0	P1	P2	t	W	K0



### IR REFLOW SOLDERING TEMPERATURE PROFILE

(One Time Reflow Soldering is Recommended)



Profile Details	Conditions
$ \begin{array}{l} \textbf{Preheat} \\ \textbf{- Min Temperature } (T_{SMIN}) \\ \textbf{- Max Temperature } (T_{SMAX}) \\ \textbf{- Time } T_{SMIN} \text{ to } T_{SMAX} \left(t_s\right) \end{array} $	150°C 180°C 60s - 120s
	260°C 217°C 20s 60s 3°C/s max 3 - 6°C/s
Average Ramp Up Rate (T <sub>smax</sub> to T <sub>P</sub> )	3°C/s max
Time 25°C to Peak Temperature	8 minutes max



### **NOTES:**

- Isocom is continually improving the quality, reliability, function or design and Isocom reserves the right to make changes without further notices.
- The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
- For equipment/application where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc., please contact our sales representatives.
- When requiring a device for any "specific" application, please contact our sales for advice.
- The contents described herein are subject to change without prior notice.
- Do not immerse device body in solder paste.



## **DISCLAIMER**

ISOCOM is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing ISOCOM products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such ISOCOM products could cause loss of human life, bodily injury or damage to property.

In developing your designs, please ensure that ISOCOM products are used within specified operating ranges as set forth in the most recent ISOCOM products specifications.

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